

ABSTRACT

The bump ball crimping apparatus of the present invention is characterized in comprising an alignment plate 31 for aligning bump balls; a crimping table 32 on which the wafer to which bump balls are to be crimped is mounted; a crimping plate 42 that

5 crimps the bump balls onto the bonding pads of the wafer; a Y-axis moving mechanism 35 that can move the alignment plate 31 in the Y direction and can fasten it at a predetermined position; an X-axis moving mechanism that can move the alignment plate 31 in the X direction and can fasten it at a predetermined position; and a second Y-axis moving mechanism 37 that can move the crimping table 32 in the Y direction

10 and can fasten it at a predetermined position.